Technical Data Sheet
EP1305 Black

01/15/2019

N109 W13300 ELLSWORTH DRIVE GERMANTOWN, WI 53022
262-253-5900 FAX 262-253-5919

DESCRIPTION:

Resinlab® EP1305 Black is a highly toughened urethane modified epoxy designed for bonding PVC, metals, ceramics and other difficult to bond substrates. The system has a thixotropic non-sag viscosity but is easily dispensed from side-by-side cartridge systems.

EP1305 Black was formulated to a 1A:1B by volume mix ratio for use in side-by-side dispensing cartridges and meter/mix and dispense equipment. EP1305 Black will reach handle cure at room temperature within 2 – 4 hours. Cure time can be accelerated by the application of heat. Times and temperatures from 2 hours at 65 °C to 1 hour at 100 °C are typical for most applications. Cooler temperatures will also extend work time and increase cure times.

TYPICAL PROPERTIES:

All properties given are at 25 °C unless otherwise noted.

Property:	*Value:*	*Test Method or Source:*
Color	Black	Visual
Mix Ratio **By weight** **By volume**	Part A to Part B 1.15 to 1 1 to 1	Calculated
Cure Schedule	Handle cure in 2-4 hours @ room temperature 2 hours @65 °C / 1 hour @ 100 °C	
Viscosity – Part A **Viscosity – Part B** **Viscosity - Mixed**	380,000 cps RVT#7@2.5pm 160,000 cps @ 1/s 170,000 cps @ 1/s 109,000 cps @ 1/s	 Rheometer parallel plate 25mm@1/s 455300006291
Specific Gravity – Part A **Specific Gravity – Part B** **Specific Gravity - Mixed**	1.18 0.99 1.08	Calculated
Pot Life, defined as the time it takes for initial mixed viscosity to double	12-15 minutes	Rheometer parallel plate 25mm@1/s 455300006291
Glass Transition Temperature/Tg	35 °C	453560822409 by DSC
Hardness	70 Shore D	455300006287/ASTM D2240
Water Absorption	0.97% after 24 hours	457561824543/ASTM D570
Tensile Properties: **Strength** **Elongation** **Modulus**	 3,500 psi 10% 128,0000 psi	455300006285/ASTM D638
Lap Shear Strength **0.010" bond line Al to Al**	 1,000 psi	455300005642/ASTM D1002 Abraded 2024 T3 Al wiped with MEK
Peel Strength	15 pli*	Estimated
Compressive Properties: **Yield Strength** **Compressive Strength** **Modulus**	 4,400 psi 22,000 psi 120,000 psi	455300006265/ASTM D695
Flame Resistance	Passes Resinlab testing with HB rating at 3mm thickness. Not UL Certified.	UL94
Thermal Conductivity by LFA	0.15 W / (m.K)	453560822409/ASTM E1461

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Surface Resistivity **Volume Resistivity**	1.61 x 10^{16} ohm/sq (@ 20 %RH) 2.1 x 10^{15} ohm-cm (@ 19 °C)	455300006612/ASTM D257
Dielectric Constant / Dissipation Factor		455300006513/ASTM D150
@ 100 Hz	4.0, 0.05	
@ 100 kHz	3.6, 0.03	
AC Dielectric Strength	440 V/mil* 17.3 kV/mm*	ASTM D149 Method A, immersed in ASTM D3487 Type II Oil Estimated
Coefficient of Thermal Expansion by TMA	90ppm/ °C below Tg 210 ppm/ °C above Tg	455300005340/ASTM E831 TMA, 5 °C/min
Temperature Range	-40 to 150 °C**	

* Asterisk denotes values considered typical to associated resin systems or extrapolated from other test results.
** Temperature Rating is based on average design requirements and is not intended as a guarantee of suitability for all applications operating at that temperature.
*** This TDS contains values that have been updated. The values reported in this technical data sheet are typical values of the product, and are highly dependent on test conditions and methodology. We actively seek the most precise and accurate ways to measure and interpret performance of our products, and to update estimated values with measured values. The formula has not been revised or changed in any way. Although the values on paper have changed, you can expect the same performance of the product.

INSTRUCTIONS:

1. Bring both components to room temperature prior to mixing. Cartridges should be stored in a vertical position to allow any air to accumulate at the tip. Mixer should be attached keeping the cartridge vertical and any air pocket purged this way. After the mixer contains material, the mixer tip can be dropped to dispense pre-bleed amount.

2. If used in bulk, weigh and mix parts A and B accurately and thoroughly, scraping sides of container often. Do not pour from mixing container, transfer to a new container as residual unmixed material may cause a tacky spot on the surface of the casting. If the product is used in a side-by-side cartridge, attach a new static mixer with each cartridge, then pre-bleed the first 3 inches of dispensed material or until a uniform color is obtained. Maintain adequate velocity during dispensing to ensure complete mixing.

3. Allow to cure undisturbed until product is fully gelled or tack-free to the touch.

4. Clean up uncured resin with suitable organic solvent such as MEK, acetone or other organic solvent.

APPLICATION NOTE: ***Do not apply to damp or wet substrates or dilute with water. Water has a negative impact on the structural integrity of the product and will lead to adhesive failure.***

SHELF LIFE AND STORAGE: 12 months at 25 °C
Specialty packaging may be less.

Many epoxy resin systems are prone to crystallization as epoxy resin is a super-cooled fluid. This condition may give the product a gritty or grainy appearance (or hazy in clear products). Products in this state will not usually cure to normal and expected properties. In extreme cases it may appear solid and cured. Fluctuating temperatures (within 5 to 50 °C) aggravate this phenomenon. Heating the individual component to 50 to 60 °C while stirring can usually restore products to original state. Storage at 25 +/- 10 °C is optimum for most products.